



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN#20240726003.1**

**Qualification of RFAB using qualified Process Technology, Die Change, and additional Assembly site (FMX) & BOM options Change Notification / Sample Request**

**Date:** July 26, 2024

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team  
SC Business Services

**20240726003.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
CD74AC05M96	NULL
CD74ACT05M96	NULL

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20240726003.1	<b>PCN Date:</b>	July 26, 2024
<b>Title:</b>	Qualification of RFAB using qualified Process Technology, Die Change, and additional Assembly site (FMX) & BOM options		
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	October 24, 2024	<b>Sample requests accepted until:</b>	August 25, 2024*

**\*Sample requests received after August 25, 2024 will not be supported.**

<b>Change Type:</b>			
<input checked="" type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Wafer Fab Materials
<input checked="" type="checkbox"/> Packing/Shipping/ Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

### PCN Details

#### Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology and additional Assembly site & BOM options for the device listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	HCMOS	150 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

	MLA	MLA new	FMX
Bond Wire composition/diameter	Cu, 0.96 mil	Cu, 0.80 mil	<b>Cu, 0.8 mil</b>

Qual details are provided in the Qual Data Section.

#### Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

#### Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

#### Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

##### RoHS

##### REACH

##### Green Status

##### IEC 62474

<input checked="" type="checkbox"/> No Change			
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**Changes to product identification resulting from this PCN:**

**Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

**Die Rev:**

**Current**

**New**

Die Rev [2P]	<b>Die Rev [2P]</b>
-	<b>A</b>

**Assembly Site Information:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
MLA	MLA	MYS	KUALA LUMPUR
<b>FMX</b>	<b>MEX</b>	<b>MEX</b>	<b>Aguascalientes</b>

Sample product shipping label (not actual product label)



**Product Affected:**

CD74AC05M96	CD74ACT05M96
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For alternate parts with similar or improved performance, please visit the product page on [TI.com](http://TI.com)

**<<< R-CHG-2406-023 qual memo here >>>**

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CD74AC05M96	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74HCS74QDRQ1	QBS Reference: SN74AC16PWRQ1	QBS Reference: CD74AC04M96
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	1/45/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	3/45/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: CD74AC05M96	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74HCS74QDRQ1	QBS Reference: SN74AC16PWRQ1	QBS Reference: CD74AC04M96
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	3/45/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	1/10/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	3/90/0	-

- QBS: Qual By Similarity
- Qual Device CD74AC05M96 is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2406-023

<<< R-CHG-2406-022 qual memo here >>>

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">CD74AC05M96</a>	QBS Reference: <a href="#">SN74HCS74QPWRQ1</a>	QBS Reference: <a href="#">LM393BIDR</a>	QBS Reference: <a href="#">SN74AC16PWRQ1</a>	QBS Reference: <a href="#">CD74AC04M96</a>	QBS Reference: <a href="#">SN74AC04PWR</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	1/45/0	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	3/231/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	3/2400/0	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">CD74AC05M96</a>	QBS Reference: <a href="#">SN74HCS74QPWRQ1</a>	QBS Reference: <a href="#">LM393BIDR</a>	QBS Reference: <a href="#">SN74AC16PWRQ1</a>	QBS Reference: <a href="#">CD74AC04M96</a>	QBS Reference: <a href="#">SN74AC04PWR</a>
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	1/10/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	2/6/0	-	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	2/6/0	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	2/6/0	1/3/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	-	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	3/90/0	-	-
FTY	E6	Final Test Yield	-	-	-	-	1/1/0	-	-	-

- QBS: Qual By Similarity
- Qual Device CD74AC05M96 is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2406-022

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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